



# 2 – 10 GHz Medium Power Gallium Arsenide FET

## Technical Data

### ATF-46101

#### Features

- **High Output Power:**  
27.0 dBm Typical  $P_{1\text{ dB}}$  at 4 GHz
- **High Gain at 1 dB Compression:**  
12.0 dB Typical  $G_{1\text{ dB}}$  at 4 GHz
- **High Power Efficiency:**  
38% Typical at 4 GHz

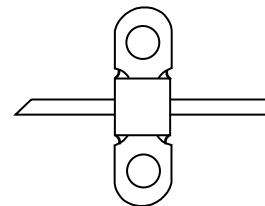
#### Description

The ATF-46101 is a gallium arsenide Schottky-barrier-gate field effect transistor designed for medium power, linear amplification in the 2 to 10 GHz frequency range. This nominally 0.5 micron

gate length GaAs FET is an interdigitated four-cell structure using airbridge interconnects between drain fingers. Total gate periphery is 1.25 millimeters. Proven gold based metallization systems and nitride passivation assure a rugged, reliable device.

This device is suitable for applications in space, airborne, military ground and shipboard, and commercial environments. It is supplied in a hermetic high reliability package with low parasitic reactance and minimum thermal resistance.

#### 100 mil Flange Package



#### Electrical Specifications, $T_A = 25^\circ\text{C}$

Symbol	Parameters and Test Conditions <sup>[1]</sup>	Units	Min.	Typ.	Max.	
$P_{1\text{ dB}}$	Power Output @ 1 dB Gain Compression: $V_{\text{DS}} = 9\text{ V}$ , $I_{\text{DS}} = 125\text{ mA}$	$f = 4.0\text{ GHz}$ $f = 8.0\text{ GHz}$	dBm	25.0	27.0 26.5	
$G_{1\text{ dB}}$	1 dB Compressed Gain: $V_{\text{DS}} = 9\text{ V}$ , $I_{\text{DS}} = 125\text{ mA}$	$f = 4.0\text{ GHz}$ $f = 8.0\text{ GHz}$	dB	9.0	10.0 5.0	
$\eta_{\text{add}}$	Efficiency @ $P_{1\text{ dB}}$ : $V_{\text{DS}} = 9\text{ V}$ , $I_{\text{DS}} = 125\text{ mA}$	$f = 4.0\text{ GHz}$	%		38	
$g_m$	Transconductance: $V_{\text{DS}} = 2.5\text{ V}$ , $I_{\text{DS}} = 125\text{ mA}$		mmho		100	
$I_{\text{DSS}}$	Saturated Drain Current: $V_{\text{DS}} = 2.5\text{ V}$ , $V_{\text{GS}} = 0\text{ V}$		mA	200	330	450
$V_p$	Pinch-off Voltage: $V_{\text{DS}} = 2.5\text{ V}$ , $I_{\text{DS}} = 5\text{ mA}$		V	-5.4	-3.5	-2.0

#### Note:

1. RF Performance is determined by packaging and testing 10 samples per wafer.

## ATF-46101 Absolute Maximum Ratings

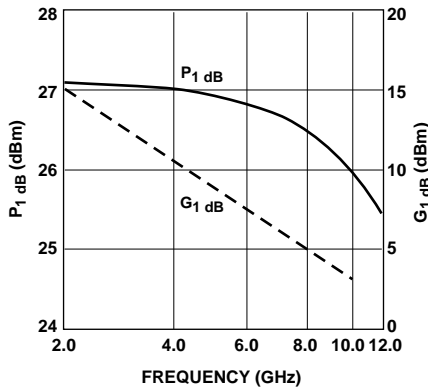
Symbol	Parameter	Units	Absolute Maximum <sup>[1]</sup>
$V_{DS}$	Drain-Source Voltage	V	+14
$V_{GS}$	Gate-Source Voltage	V	-7
$V_{GD}$	Gate-Drain Voltage	V	-16
$I_{DS}$	Drain Current	mA	$I_{DSS}$
$P_T$	Power Dissipation <sup>[2,3]</sup>	W	2.0
$T_{CH}$	Channel Temperature	°C	175
$T_{STG}$	Storage Temperature	°C	-65 to +175

**Thermal Resistance:**  $\theta_{jc} = 75^\circ\text{C/W}$ ;  $T_{CH} = 150^\circ\text{C}$   
**Liquid Crystal Measurement:**  $1\ \mu\text{m}$  Spot Size<sup>[4]</sup>

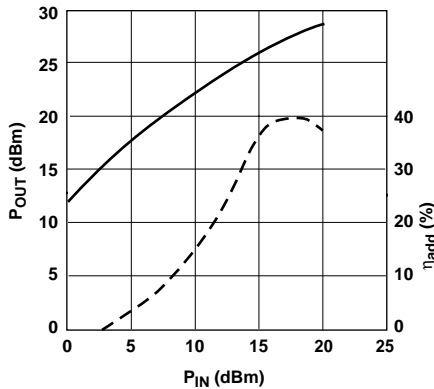
### Notes:

1. Permanent damage may occur if any of these limits are exceeded.
2.  $T_{\text{MOUNTING SURFACE}} = 25^\circ\text{C}$ .
3. Derate at  $13\ \text{mW}/^\circ\text{C}$  for  $T_{\text{CASE}} > 25^\circ\text{C}$ .
4. The small spot size of this technique results in a higher, though more accurate determination of  $\theta_{jc}$  than do alternate methods. See MEASUREMENTS section for more information.

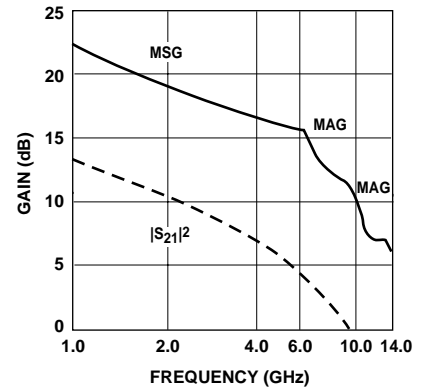
## ATF-46101 Typical Performance, $T_A = 25^\circ\text{C}$



**Figure 1. Power Output @ 1 dB Gain Compression and 1 dB Compressed Gain vs. Frequency.**  
 $V_{DS} = 9\ \text{V}$ ,  $I_{DS} = 125\ \text{mA}$ .



**Figure 2. Output Power and Power Added Efficiency vs. Input Power.**  
 $V_{DS} = 9\ \text{V}$ ,  $I_{DS} = 125\ \text{mA}$ ,  $f = 4.0\ \text{GHz}$ .

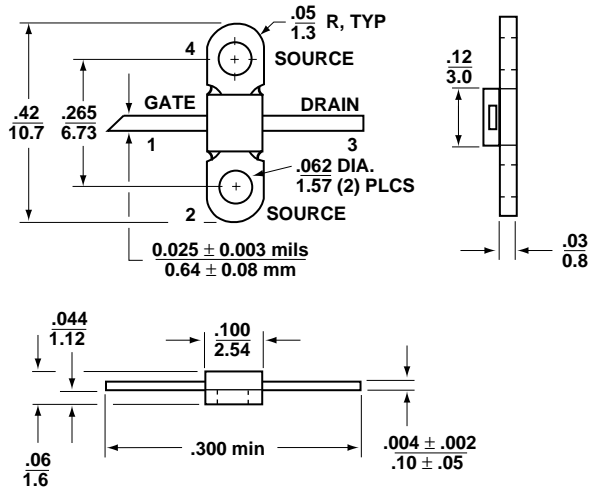


**Figure 3. Insertion Power Gain, Maximum Available Gain and Maximum Stable Gain vs. Frequency.**  
 $V_{DS} = 9\ \text{V}$ ,  $I_{DS} = 125\ \text{mA}$ .

**Typical Scattering Parameters, Common Emitter,  $Z_O = 50 \Omega$ ,  $T_A = 25^\circ\text{C}$ ,  $V_{DS} = 9 \text{ V}$ ,  $I_{DS} = 125 \text{ mA}$** 

Freq. GHz	$S_{11}$		$S_{21}$			$S_{12}$			$S_{22}$	
	Mag.	Ang.	dB	Mag.	Ang.	dB	Mag.	Ang.	Mag.	Ang.
1.0	.94	-56	12.8	4.37	135	-31.4	.027	52	.64	-28
2.0	.86	-101	10.7	3.41	98	-27.3	.043	30	.59	-56
3.0	.82	-131	8.4	2.64	71	-26.9	.045	18	.58	-79
4.0	.82	-152	6.7	2.16	48	-26.4	.048	9	.62	-98
5.0	.80	-173	5.4	1.86	26	-26.0	.050	-1	.63	-112
6.0	.79	165	4.3	1.64	5	-25.8	.051	-12	.65	-126
7.0	.78	143	3.1	1.43	-18	-25.4	.054	-24	.65	-145
8.0	.78	131	1.6	1.20	-36	-24.7	.058	-37	.70	-166
9.0	.77	123	0.3	1.03	-55	-23.9	.064	-40	.73	173
10.0	.76	118	-1.2	.87	-72	-23.1	.070	-52	.76	158
11.0	.67	104	-2.0	.79	-91	-22.6	.074	-57	.79	146
12.0	.60	86	-2.7	.73	-110	-21.2	.087	-66	.83	136
13.0	.54	71	-3.5	.67	-133	-19.7	.104	-79	.87	124
14.0	.50	64	-4.0	.63	-154	-15.9	.160	-99	.92	115

A model for this device is available in the DEVICE MODELS section.

**100 mil Flange Package Dimensions**


- Notes:  
(unless otherwise specified)
1. Dimensions are  $\frac{\text{in}}{\text{mm}}$
  2. Tolerances  
in .xxx =  $\pm 0.005$   
mm .xx =  $\pm 0.13$

Package marking code is 461



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